

3A, 50V - 1000V Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Low forward voltage drop
- High surge current capability
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.09 g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_{F(AV)}$	3	A
V_{RRM}	50 - 1000	V
I_{FSM}	80	A
T_{JMAX}	150	°C
Package	DO-214AA (SMB)	
Configuration	Single Die	



DO-214AA (SMB)

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)									
PARAMETER	SYMBOL	S3AB	S3BB	S3DB	S3GB	S3JB	S3KB	S3MB	UNIT
Marking code on the device		S3AB	S3BB	S3DB	S3GB	S3JB	S3KB	S3MB	
Repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Forward current	$I_{F(AV)}$	3							A
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I_{FSM}	80							A
Junction temperature	T_J	- 55 to +150							°C
Storage temperature	T_{STG}	- 55 to +150							°C

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-lead thermal resistance	$R_{\theta JL}$	10	°C/W

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage per diode ⁽¹⁾	$I_F = 3\text{A}, T_J = 25^\circ\text{C}$	V_F	-	1.15	V
Reverse current @ rated V_R per diode ⁽²⁾	$T_J = 25^\circ\text{C}$	I_R	-	10	μA
	$T_J = 125^\circ\text{C}$		-	250	μA
Junction capacitance	1 MHz, $V_R = 4.0\text{V}$	C_J	40	-	pF
Reverse recovery time	$I_F = 0.5\text{A}, I_R = 1.0\text{A}$ $I_{RR} = 0.25\text{A}$	t_{rr}	1500	-	ns

Notes:

1. Pulse test with $PW = 0.3\text{ ms}$
2. Pulse test with $PW = 30\text{ ms}$

ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX(*)	PACKAGE	PACKING
S3xB (Note 1)	H	R5	G	SMB	850 / 7" Plastic reel
		R4		SMB	3,000 / 13" Paper reel
		M4		SMB	3,000 / 13" Plastic reel

Note:

1. "x" defines voltage from 50V (S3AB) to 1000V (S3MB)
- *: Optional available

EXAMPLE P/N					
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
S3ABHR5G	S3AB	H	R5	G	AEC-Q101 qualified Green compound

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

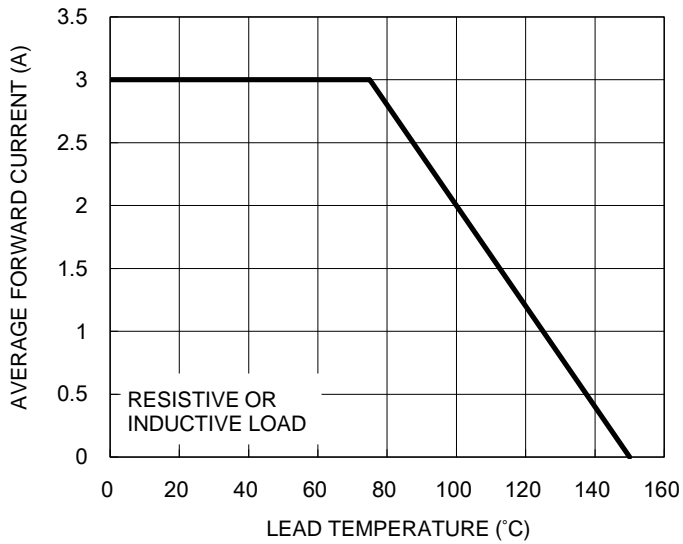


Fig.2 Typical Junction Capacitance

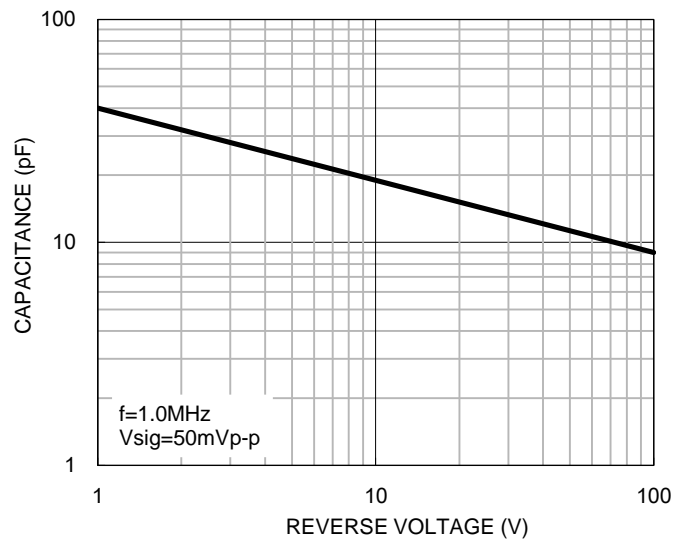


Fig.3 Typical Reverse Characteristics

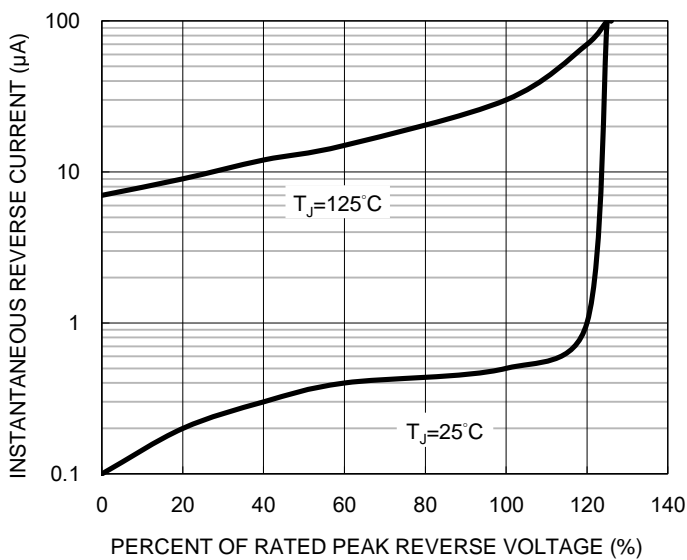


Fig.4 Typical Forward Characteristics

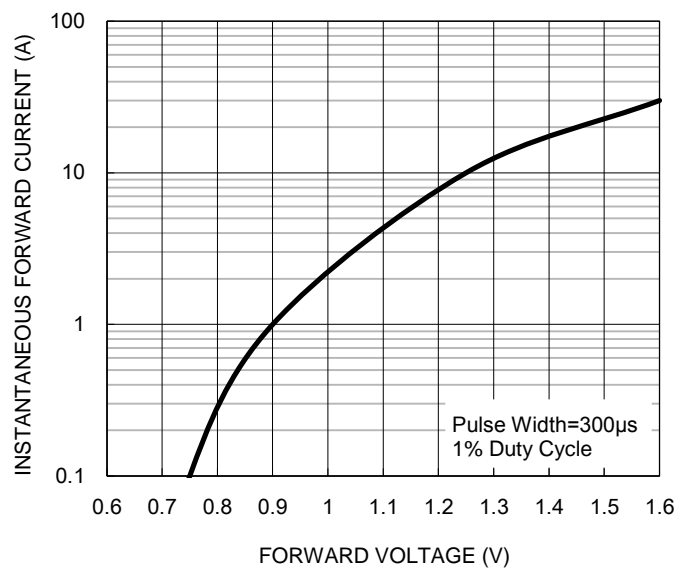


Fig.5 Maximum Non-repetitive Forward Surge Current

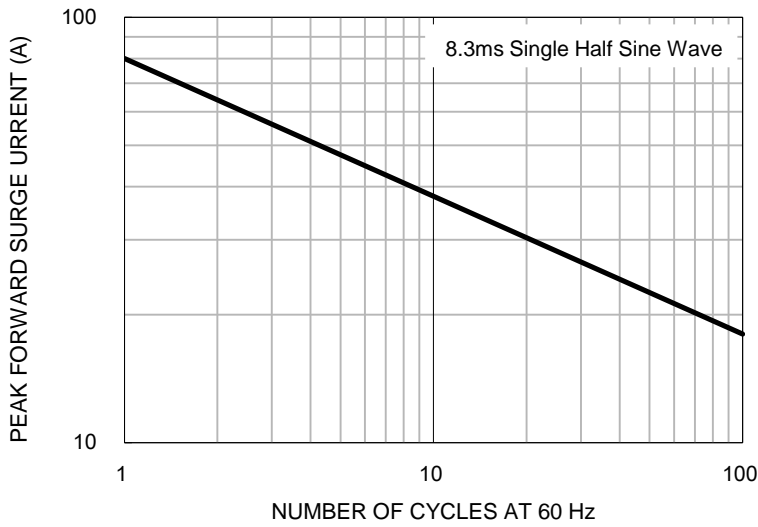
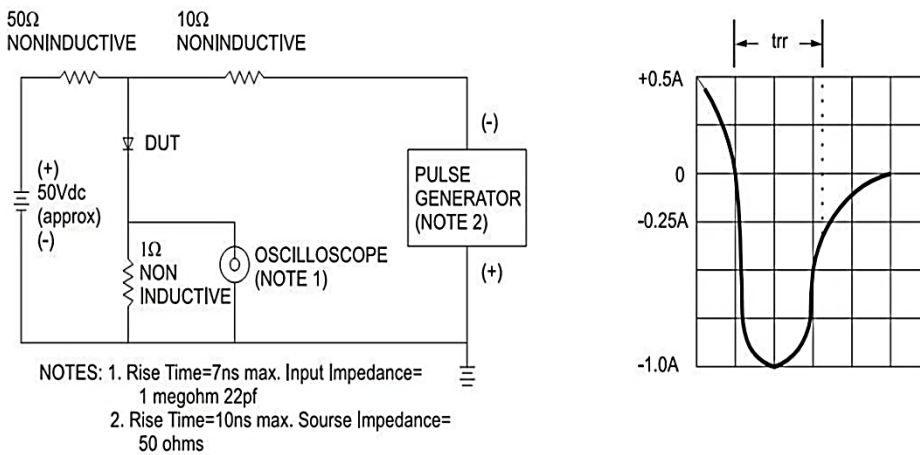


Fig.6 Reverse Recovery Time Characteristic And Test Circuit Diagram



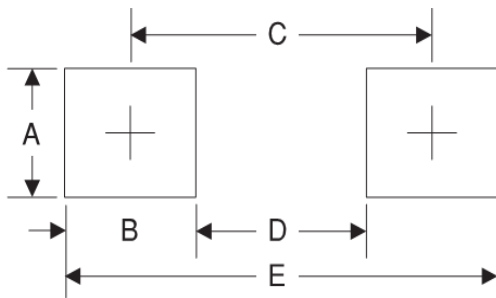
PACKAGE OUTLINE DIMENSIONS

DO-214AA (SMB)



DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	1.95	2.20	0.077	0.087
B	4.05	4.60	0.159	0.181
C	3.30	3.95	0.130	0.156
D	1.95	2.65	0.077	0.104
E	0.75	1.60	0.030	0.063
F	5.10	5.60	0.201	0.220
G	0.05	0.20	0.002	0.008
H	0.15	0.31	0.006	0.012

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.3	0.091
B	2.5	0.098
C	4.3	0.169
D	1.8	0.071
E	6.8	0.268

MARKING DIAGRAM



- P/N = Marking Code
- G = Green Compound
- YW = Date Code
- F = Factory Code

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